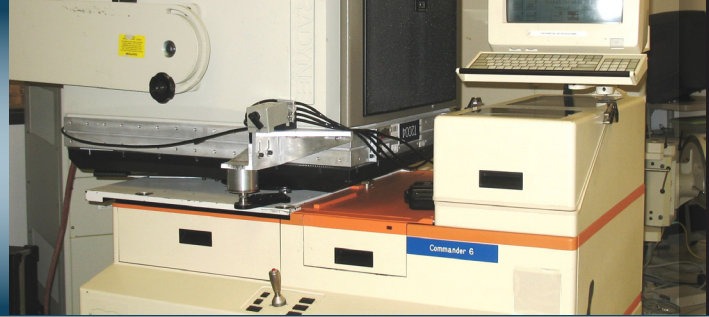


**INTEGRA**  
TECHNOLOGIES



## WAFER PROBE

Integra has the engineering talent, equipment and processes in place to support all probe services, including software development, probe card design / fab, debug and production probing.

We are a one stop shop for all your probe card design, fabrication, verification and production needs.

### Experience with all probe card technologies including:

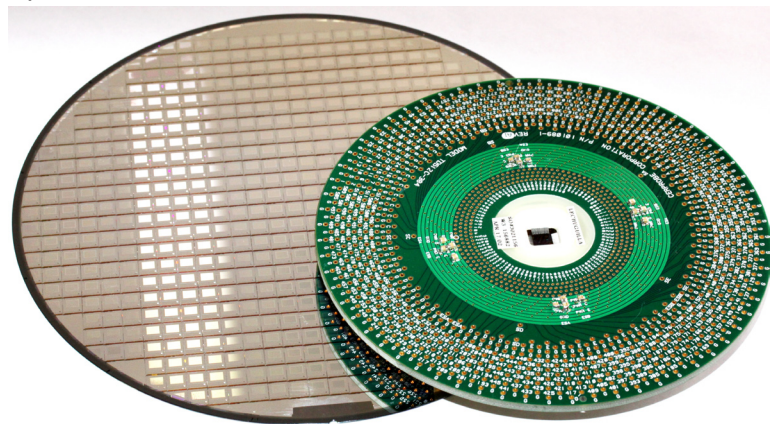
- Cantilever: 1- 8 sites up to 800 probes
- Vertical: Multi site
- Membrane: Multi site
- RF: Coax, Membrane and Custom solutions
- Elevated probing up to 135°C and custom probing up to 180°C

### Probe data analysis throughout your startup and ongoing production probe:

- Wafer Map Conversion
- Retest of defined bins without full wafer reprobe.
- Custom mapping for inkless assembly.
  - Onsite custom format solutions for inkless assembly
  - Assembly back to production map conversion
  - Wafer inspection map conversion to electrical test maps
- Wafer Analysis
  - Composite Mapping
  - Multi site comparison
  - Integration to Galaxy® software

### Summary of probe capabilities:

- 3" to 12" capability
- Probe card design, fab and verification
- Bumped probe
- Al, Au pads and Pb, Pb free bumps
- High Z force chuck
- High pin count, fine pitch
- Multi site
- Vertical, Cantilever & Membrane probe
- RF probe (Membrane, Coax or custom solutions)
- N2 and vacuum wafer storage
- Elevated probing up to 180°C
- Data analysis capability
- High volume production probe
- Handle wafer back grind to 6 mils



Celebrating over 25 years of providing high quality semiconductor test services.

*For more information, call our US based test facilities at 1-800-622-2382*

[www.Integra-Tech.com](http://www.Integra-Tech.com)

Wafer Probe DS Rev 02 06 09